

<b>Notice of References Cited</b>		Application/Control No. 10/539,260	Applicant(s)/Patent Under Reexamination HAISMA, JAN	
		Examiner JONATHAN C. LANGMAN	Art Unit 1794	Page 1 of 1

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*	C US-6,544,863	04-2003	Chong et al.	438/455
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M	US-			

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**NON-PATENT DOCUMENTS**

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U	Spiering et al. "Sacrificial wafer bonding for planarization after very deep wafer etching" all teach the structures being formed in the handle wafer and not being formed of the intermediate or insulating layer". Journal of Microelectromechanical Systems., vol. 4, no.3, 1995, pgs 151-157.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a))  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.